Willkommen bei O-Leading

Wir sind professioneller Leiterplattenhersteller mit mehr als zehn Jahren Erfahrung. Einzelne Produktreihe, doppelseitige, mehrschichtige Leiterplatte, flexible Leiterplatte und MCPCB. Wir bieten schnellen Prototypservice - S / S in 24 Stunden, 4-8 Schichten in 48-96 Stunden Produktionszeit.

KUPFERPLATTENLÖCHER MINDEST .025 AVG, .020 MIN. LÖCHER DÜRFEN NICHT GESTROMT WERDEN

Packen Sie mit farbloser, transparenter Luftpolsterfolie, 25 Stck./Tasche, Trockenmittel in die Flanke, setzen Sie die Feuchtigkeitsanzeige auf die Oberseite

BITTE KLICKEN SIE FÜR WEITERE INFORMATIONEN

Dicke kupfer pcb hersteller

Starke kupferne Leiterplatte in China

Hersteller von Leiterplatten

Produktbeschreibung

PCB P / N	schwere kupferleiterplatte mit 3 / 3oz
Schichtanzahl	2L
Material	FR-4 TG130
Board thk	1,00 mm
kupfer thk	3 / 3oz
Kleinste Lochgröße	0,50 mm
Anzahl der Löcher (Stck)	106
Zeile w / s	10/10 mil
Impedanzkontrolle J / N (Tol%)	N
Oberflächenveredelung	LF-HASL
Lötmaske-Siebdruck	Grün / N / A
Einzelplatinengröße	Dim X (mm): 44,5; Dim Y (mm): 34
Panelisierung	Dim X (mm): 198; Dim Y (mm): 156; Anzahl der USV: 16
Besonderheit: abziehbare Maske	N
Routing / Lochen	CNC

-

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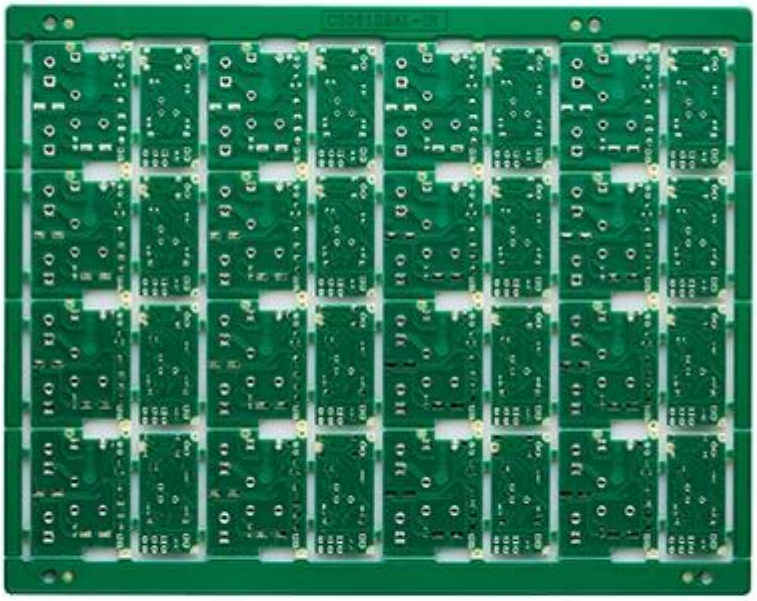

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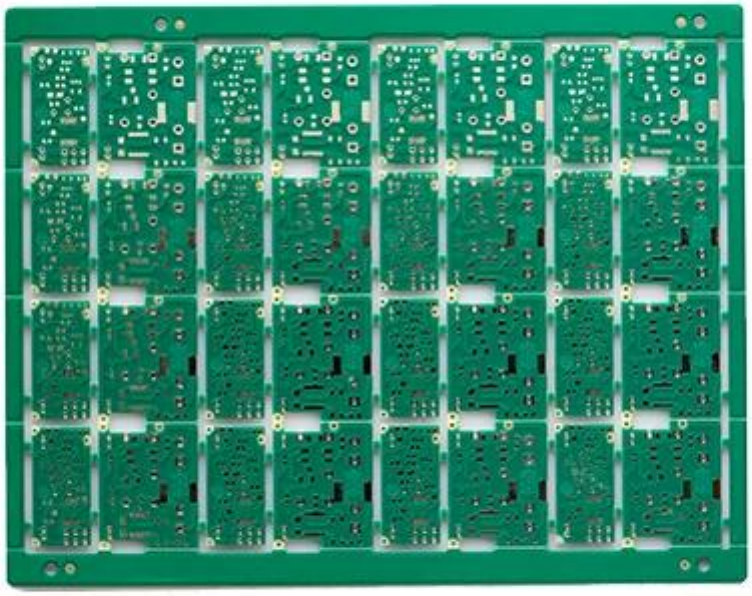

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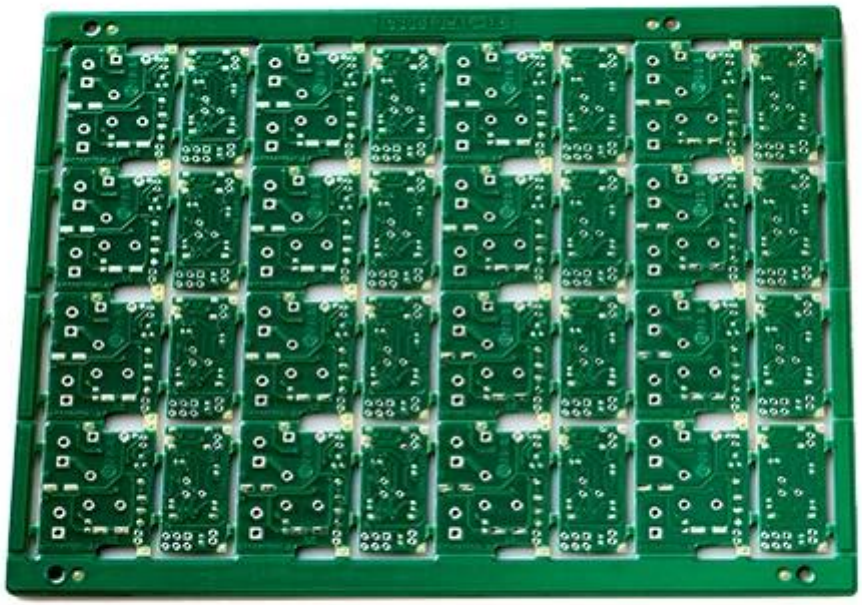

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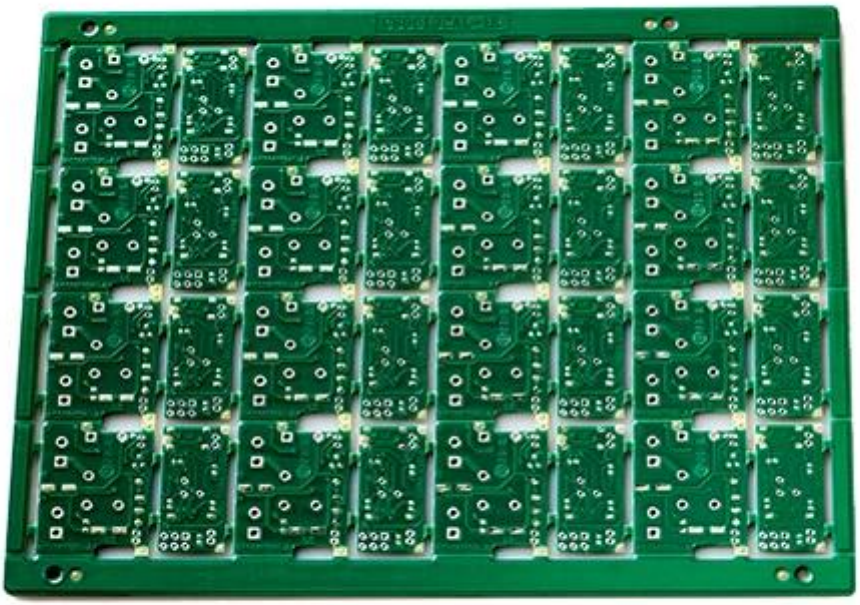

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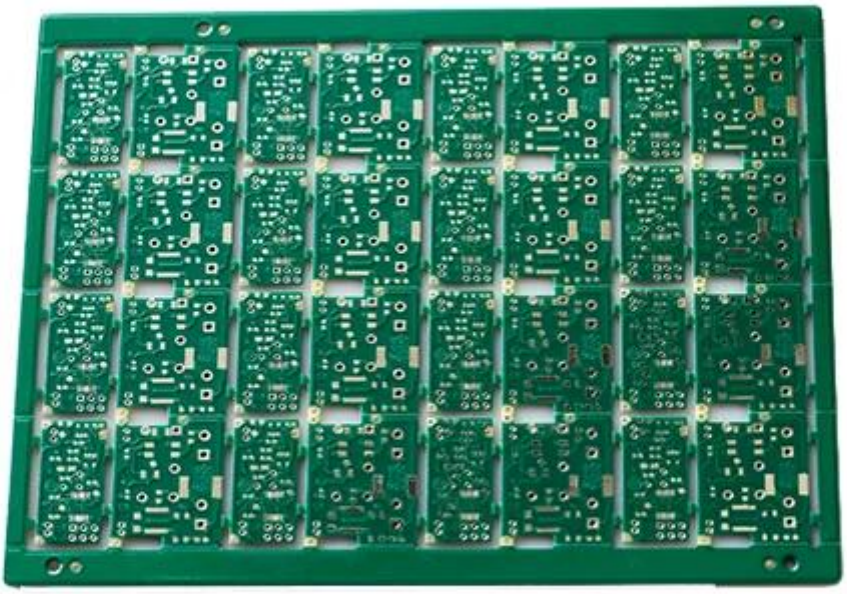

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Unser Team

Zertifizierungen

Quality Management System Certificate

This is to certify that
(Organization Code Certificate : 61691591-000-07-16-8)

O-LEADING SUPPLY CHAIN (HK) CO.,LIMITED

ROOM 603D, 6/F HANG PONT COMMERCIAL BUILDING, 31 TONKIN ST., CHEUNG SHA WAN, KL, HK

has been established the quality management system meeting the requirements of standard

GB/T19001-2008/ISO9001:2008

Scope:

Certification Address: Room 1313, Fortune Building, Nanheng West Road, Huiyang District, Huizhou, Guangdong, China

Certification Activities: Sales and services of printed circuit boards

Certificate No.: 51816Q01163R0S

Issued Date : 2016-11-17 **Valid to :** 2018-09-15

Initial Issued Date : 2016-11-17 **Renewal Date :** ***

GM

CICC INSPECTION CERTIFICATION

CICC CERTIFICATION 嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R0S

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-17-2

Registration Add:ROOM 603D,6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL,HK

Business Add:1313,Floor 13,Fortune Building,Danshui Town,Huiyang District, Huizhou,Guangdong,China

Has implemented and maintains a **Quality Management System**
Which fulfils the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification

Sales of printed circuit boards

Initial Issuance period: February 27, 2018
This certificate is valid during: February 27, 2018 — February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark

The certification registration scope doesn't include those product/service scopes which fail to be covered by the relevant effective administration permission and qualification permission regulated by the state.
The effectiveness of this certificate shall be validated by annual surveillance audit of CICC the certificate shall be valid that used together with the surveillance audit conclusion.
The related information of this certification can be searched at the portal
On the site of company www.cicc-hk.com

CICC CERTIFICATION IAF CNAS

2017/2/6 ZPMV2.E490354 - Wiring, Printed - Component

UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit UL's iQ™ Family of Databases.
Click on a product designation for complete information.
Page Bottom

Wiring, Printed - Component

See General Information for Wiring, Printed - Components

O-LEADING SUPPLY CHAIN CO LIMITED E490354
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

	Cond Width				Max			Max			
		Min	Cond	SS/	Area	Solder		Oper		Meets	C
	Min	Edge	Thk	DS/	Diam	Limits		Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:135	DS	50.8 (2.0)	260	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.8 (2.7)	260	10	130	V-0	All	-
O-LEADING-206											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last Updated on 2017-01-27

Questions? Print this page Terms of Use Page Top

SGS

Test Report No. CANEC1805164701 Date: 03 Apr 2018 Page 2 of 6

Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	CAN18-051647.001	Green "PCB"

Remarks :

(1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017 , IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES , UV-Vis and GC-MS .

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

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Member of the SGS Group (SGS SA)

Verpackung & Lieferung

Verpackungsinformationen	16 Jahre professioneller OEM Leiterplattenhersteller
Lieferungsdetails	7-12days

FAQ

1. Wie sichert O-Leading Qualität?
Unser hoher Qualitätsstandard wird mit folgendem erreicht.
1. Der Prozess wird streng nach ISO 9001: 2008 Standards kontrolliert.
2. Umfassender Einsatz von Software zur Verwaltung des Produktionsprozesses
3. Stand der Technik Testgeräte und Werkzeuge. Z.B. Flying Probe, Röntgeninspektion, AOI (Automated Optical Inspector) und ICT (In-Circuit-Test).
4. engagiertes qualitätssicherungsteam mit fehlerfallanalyseprozess
5. Kontinuierliche Schulung und Schulung des Personals

2. Wie hält O-Leading Ihren Preis wettbewerbsfähig?
Im letzten Jahrzehnt hatten sich die Preise vieler Rohstoffe (z. B. Kupfer, Chemikalien) verdoppelt, verdreifacht oder vervierfacht. Chinesische Währung RMB hatte 31% gegenüber dem US-Dollar aufgewertet; Und unsere Arbeitskosten sind auch deutlich gestiegen. O-Leading hat jedoch unsere Preise stabil gehalten. Dies trägt ganz zu unseren Innovationen bei der Kostenreduzierung, der Vermeidung von Verschwendung und der Verbesserung der Effizienz bei. Unsere Preise sind in der Branche auf dem gleichen Qualitätsniveau sehr wettbewerbsfähig.
Wir glauben an eine Win-Win-Partnerschaft mit unseren Kunden. Unsere Partnerschaft ist für beide Seiten von Vorteil, wenn wir Ihnen einen Kosten- und Qualitätsvorteil bieten können.

3. Welche Arten von Boards können von O-Leading verarbeitet werden?
Gängige FR4-, High-TG- und halogenfreie Platinen, Rogers, Arlon, Telfon, Platinen auf Aluminium- / Kupferbasis, PI usw.

4. Welche Daten werden für die Leiterplattenproduktion benötigt?
Es ist am besten, Daten im Gerber 274-X-Format bereitzustellen. Darüber hinaus können Cam350, CAD, Protel 99se, PADS, DXP und Eagle verarbeitet werden.

5. Was ist der typische Prozessablauf für mehrschichtige Leiterplatten?
Materialschneiden → Innerer Trockenfilm → Inneres Ätzen → Inneres AOI → Multi-Bond → Schichtstapel Pressen → Bohren → PTH → Plattieren → Äußerer Trockenfilm → Musterplattieren → Äußeres Ätzen → Äußeres AOI → Lötmaske → Bauteilmarkierung → Oberflächenfinish → Routing → E / T → Sichtprüfung.